



# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

**[List multiple models if applicable.]**

HP ProBook 470 G1 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother Board	1
Batteries	All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps Panel	1
Cathode Ray Tubes (CRT)	No	0
Capacitors / condensers (Containing PCB/PCT)	No	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	No	0
External electrical cables and cords	No	0
Gas Discharge Lamps	No	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	No	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. No	0
Components and waste containing asbestos	No	0
Components, parts and materials containing refractory ceramic fibers	No	0

Components, parts and materials containing radioactive substances	No	0
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 T8 Trox screwdriver	T8
Description #2 Cross screwdriver	#1
Description #3 Nipper	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release Battery and Access Door
2. Release ODD Module and HDD Module
3. Release Keyboard Module
4. Disassemble U-case Ass'y from L case Ass'y (MB)
5. Disassemble MB from L-case Ass'y
6. Disassemble Hinge Up from L-case Ass'y
7. DisassemblyHinge Up
8. DisassemblyBezel
9. Disassembly LCD/ Hinge Module

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

# 2013 Ricochet/ Fraser 17” Disassembly Report



*SME: Alfred Yang*

*Date:2013/01/24*

**wistron**



## **Disassembly Procedure:**

- 1. Release Battery and Access Door**
- 2. Release ODD Module and HDD Module**
- 3. Release Keyboard Module**
- 4. Disassemble U-case Ass'y from L case Ass'y (MB)**
- 5. Disassemble MB from L-case Ass'y**
- 6. Disassemble Hinge Up from L-case Ass'y**
- 7. DisassemblyHinge Up**
- 8. DisassemblyBezel**
- 9. Disassembly LCD/ Hinge Module**

## 1st Step: Release Battery and Access Door

1. Push battery knob inside to release battery
2. Push battery knob inside to release door after battery released

1

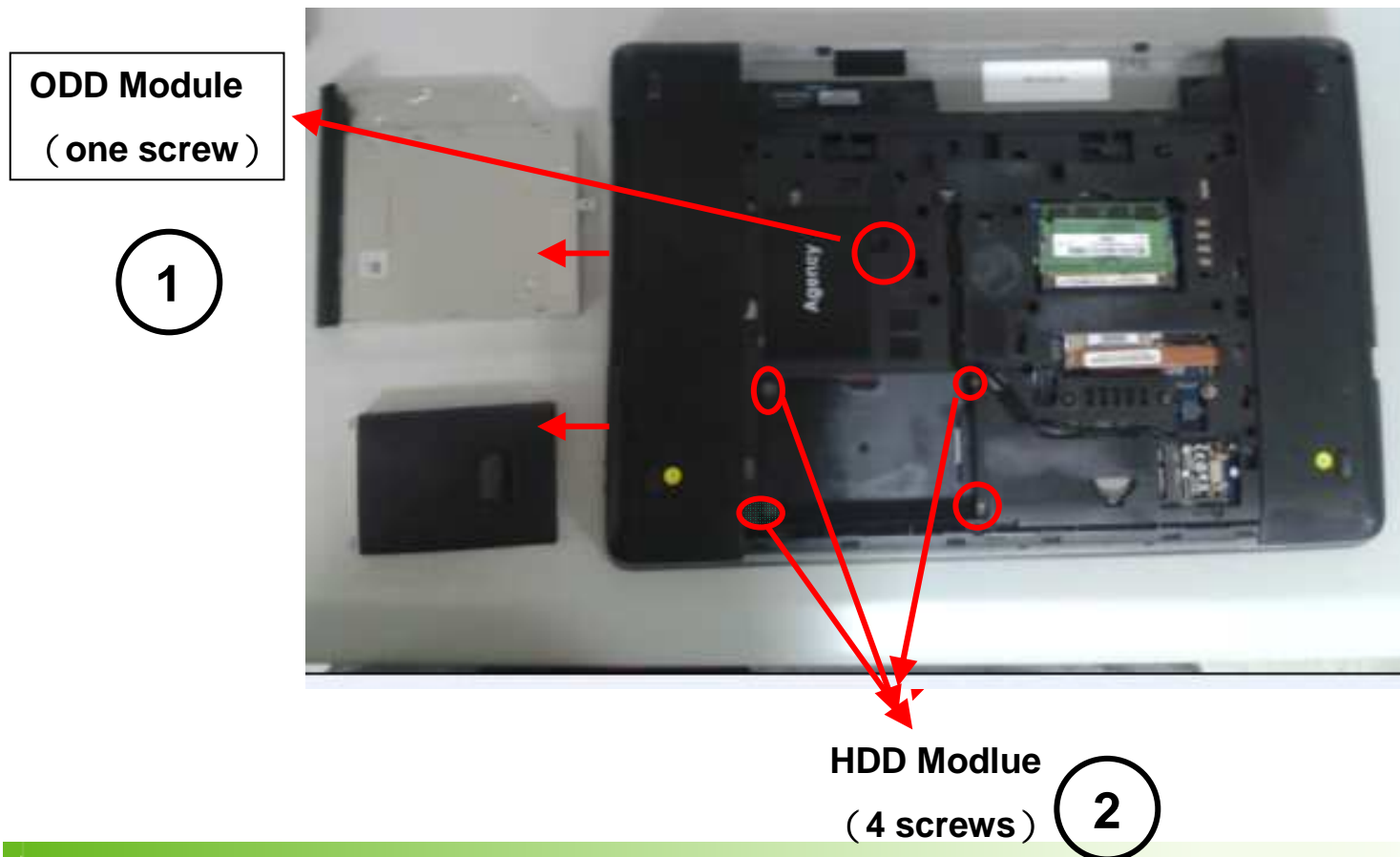


2



## 2nd Step: Release ODD Module and HDD Module

1. Loose one ODD screw, then push ODD module bracket to release ODD
2. Loose 4 HDD screws, then pull HDD mylar tap left to release HDD



### 3rd Step: Release Keyboard Module

1. **Loose 2 screws for keyboard, then push keyboard down (palm rest direction) and release keyboard membrane, then release keyboard**

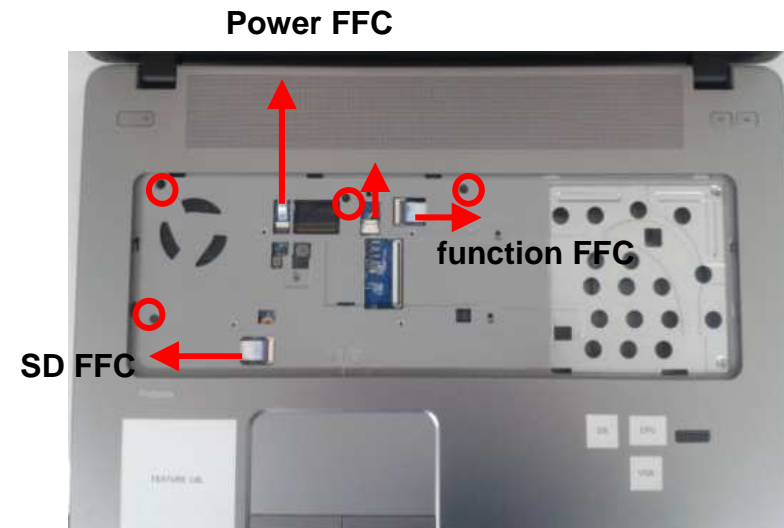
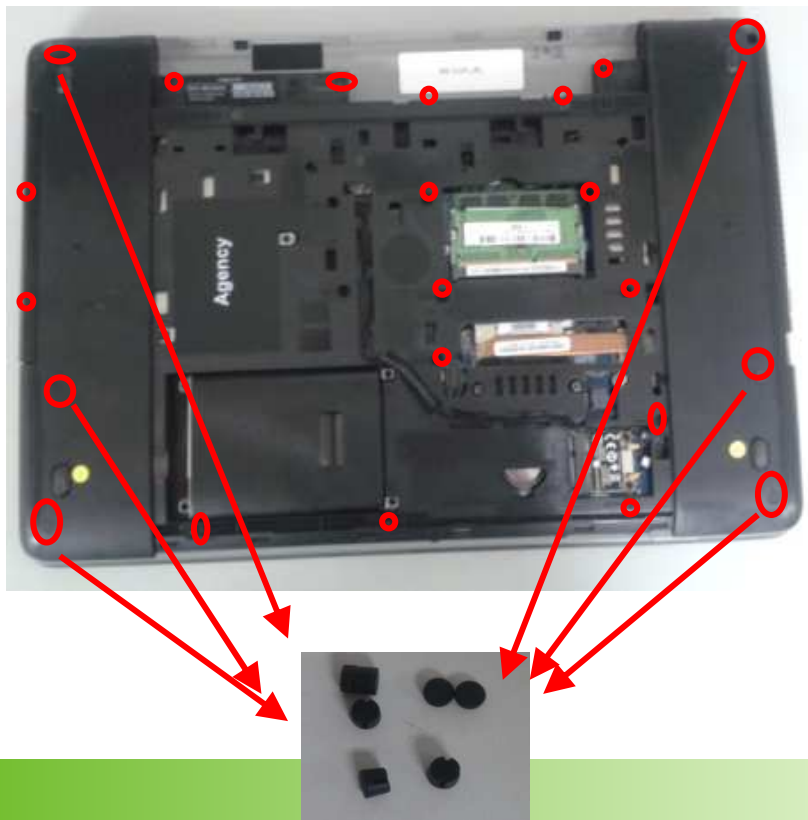


keyboard Module  
( 2 screws )



## 4th Step: Disassemble U-case Ass'y from L case Ass'y (MB)

1. Take off the 6 rubber feet, and then loose 22 screws at bottom and 4 screws on top, then follow arrow direction to release SD FFC, power FFC and function FFC.





## 4th Step: Disassemble U-case Ass'y from L case Ass'y

**2. Open the U-case, find and release USB FFC from MB connector**

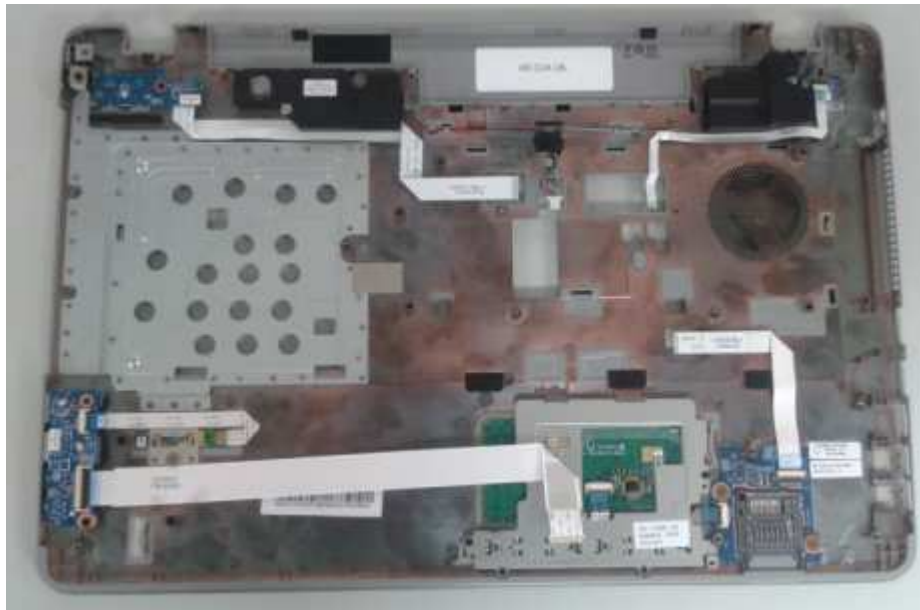


**USB FFC**

## 4th Step: Disassemble U-case Ass'y from L case Ass'y (MB)

### 3. Disassemble U-case ass'y from L-case ass'y (MB)

U-case ass'y

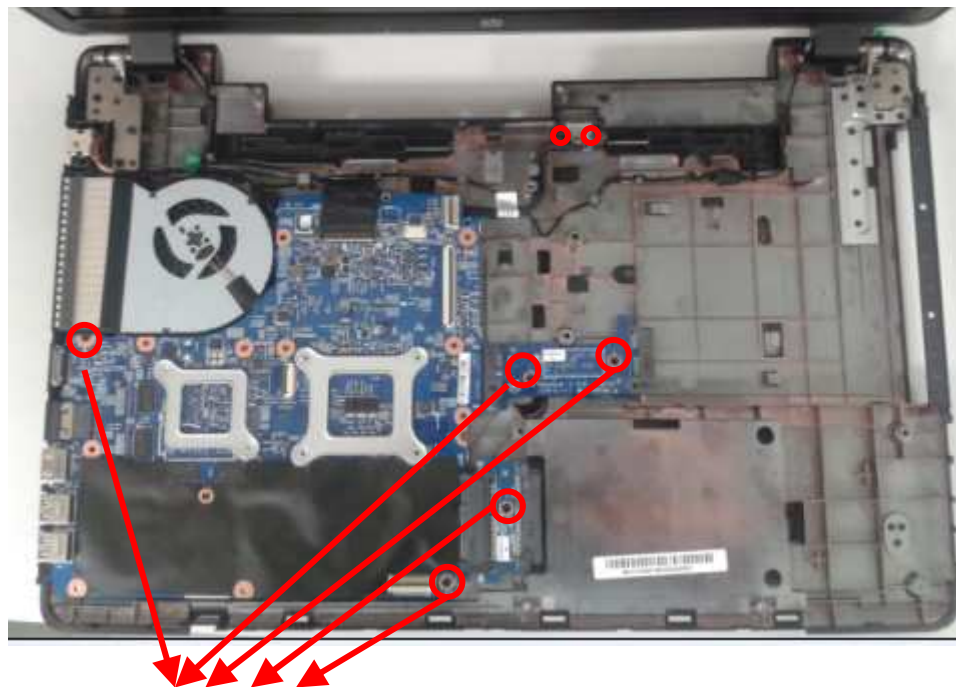


L-case ass'y with MB



## 5th Step: Disassemble MB from L-case Ass'y

1. Loose 7 screws (MBX2, HDD BDX1, ODD BDX2)
2. Release LVDS cable
3. Loose 2 screws for battery connector
4. disassemble MB from L-case



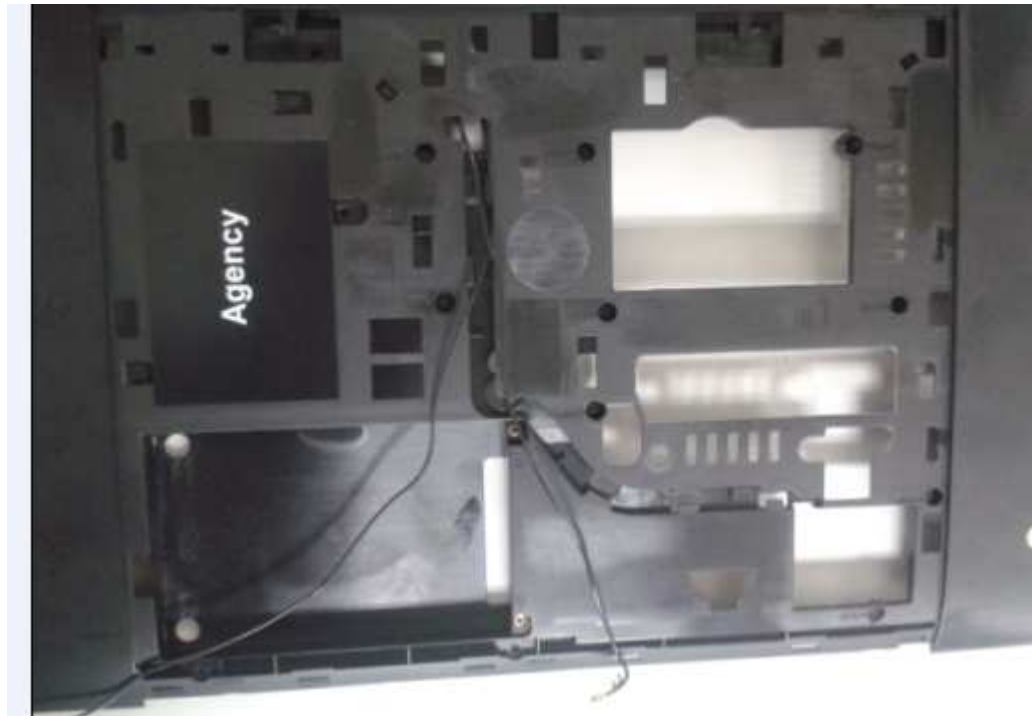
5 MB screw



## 6th Step: Disassemble Hinge Up from L-case Ass'y

1. Release 2 antenna cables from cable groove at bottom of L-case ass'y

1



## 6th Step: Disassemble Hinge Up from L-case Ass'y

2. Loose 6 hinge screws from L-case & Hinge

3. Take hinge up from L-case ass'y

2



3



L-case ass'y



Hinge Up



## 7th Step: Disassembly Hinge Up

### 1. Disassemble 2 hinge caps from hinge up



Hinge cap L  
Hinge cap R

## 8th Step: Disassembly Bezel

1. Loose the 2 screw mylar
2. Loose 2 screws to disassemble bezel



## 9th Step: Disassembly LCD/ Hinge Module

1. Loose 6 hinge screws
2. Release camera connector and take LCD/ hinge module from LCD cover ass'y

